

TOSHIBA SEMICONDUCTOR (WUXI) CO., LTD.NO.21 MINING ROAD, WUXI HIGH-TECH INDUSTRIAL
DEVELOPMENT ZONE WUXI JIANGSU CHINA

TEL: (0510) 8522-4137

FAX: (0510) 8522-5221

TO: _____

Date: Apr. 09, 2013

RefNo. TSW-PCN130409-b

PROCESS CHANGE NOTICE (PCN)**Re: Add A New Production Line for TB6551FG(O,EL,DRY)**

We are informing that we plan to add a new production line for TB6551FG(O,EL,DRY) .

We hope you will kindly approve and complete some preparation at the earliest convenience.

1. Contents of change

Item	Present (OITA)	After Change (TSW)
Product Name	TB6551FG (O,EL,DRY)	TB6551FAG(C8OEL,HZ)
Assembly Factory Name	(OITA): TOSHIBA COOPERATION SEMICONDUCTOR COMPANY OITA OPERATIONS., JAPAN	(TSW):TOSHIBA SEMICONDUCTOR(WUXI),CHINA
Wafer Factory Name [Wafer Size]	(OITA): TOSHIBA COOPERATION SEMICONDUCTOR COMPANY OITA OPERATIONS., JAPAN [6Inch]	(OITA): TOSHIBA COOPERATION SEMICONDUCTOR COMPANY OITA OPERATIONS., JAPAN [8Inch] (Refer to page 2)
Lead plate	Sn-Ag Plate	Pure-Sn Plate (Refer to page 2)
Leadframe Material	NSD	Cu (Refer to page 2)
Wire Material	Au wire	Cu wire (Refer to page 2)
Product Identification	Marking/Label	(Refer to page 3)
PKG Dimensions	Details are as follows	(Refer to Page 4)

2. Purpose of change

In order to add a production line for TB6551FG(O,EL,DRY) .

3. Schedule of change

According to sales indication .

4. Quality Assurance Policy

Quality assurance of product is the same as the original product.

5. Our Request

Your immediate approval would be very helpful to advance the new production line foundation.

So please return this PCN form to our sales office with your signature as receipt at the end of Apr, 2013.

Any questions please feel free to contact our sales office.

Thank you very much for your cooperation and we are sorry for any inconvenience caused.



Yasuro Hatori, Senior Manager of QA Department.
TOSHIBA SEMICONDUCTOR (WUXI) CO., LTD.
(DATE) Apr. 09, 2013

To: QA Department, TOSHIBA SEMICONDUCTOR (WUXI) CO., LTD.

HERE IS OUR RESPONSIBLE ENGINEER SIGN OFF

SIGNATURE _____ DATE _____

TITLE/POSITION _____

(YOUR COMMENT)

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➤ **Oita 6 inch → Oita 8 inch**

Circuit/ lay out	Process	Dummy pattern	Chip ring*2
No Change	Etch back to CMP	Add pattern*1	Change

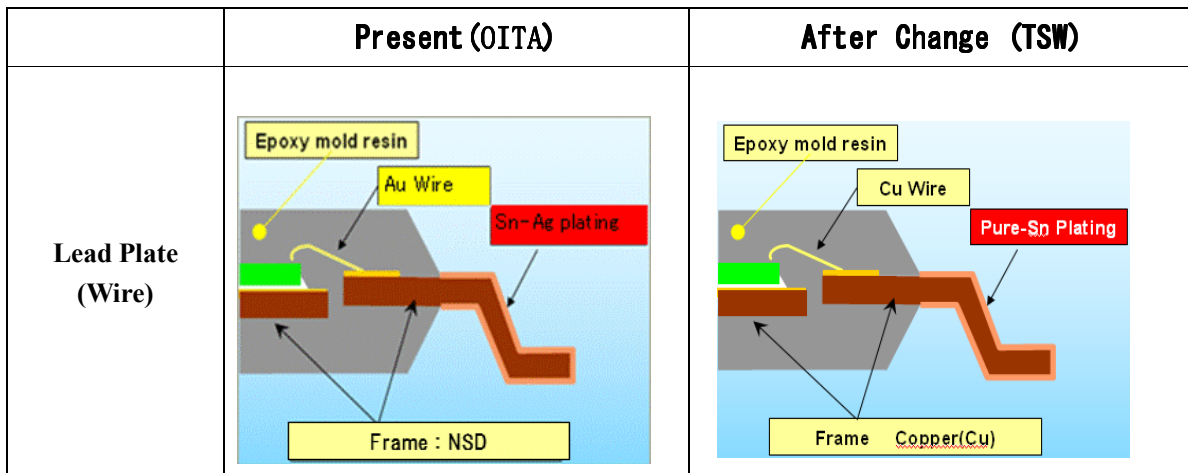
*1 Add pattern :

Addition of dummy pattern improves the wafer flatness stability and does not effect the electrical circuit area.

*2 Add ring :

Addition of chip ring improves the wafer flatness stability and does not effect the electrical circuit area.

➤ **Lead Plate(Wire)**



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➤ **Product Identification**

	Present (OITA)	After Change (TSW)
Marking	 <p>XXX: Weekly code G: Factory code XXX: Assembly code</p>	 <p>\$**: Weekly code Y: Factory code XXX: Assembly code</p>
Label (OITA)		
Label (TSW)		

Comment : Marking and inner label carton label just for reference.

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➤ **PKG Dimensions Compare**

Item	Remark No.	Dimension (Unit: mm)	
		Present (OITA)	After Change (TSW)
Mold Body Thickness	①	1.8±0.2	1.8±0.1
Full Thickness	②	2.2MAX	1.92MAX
Lead Thickness	③	0.15+0.1/-0.05	0.15~0.30
Lead Skew	④	-	0~8°
Lead length C	⑤	0.525±0.2	0.33~0.73

